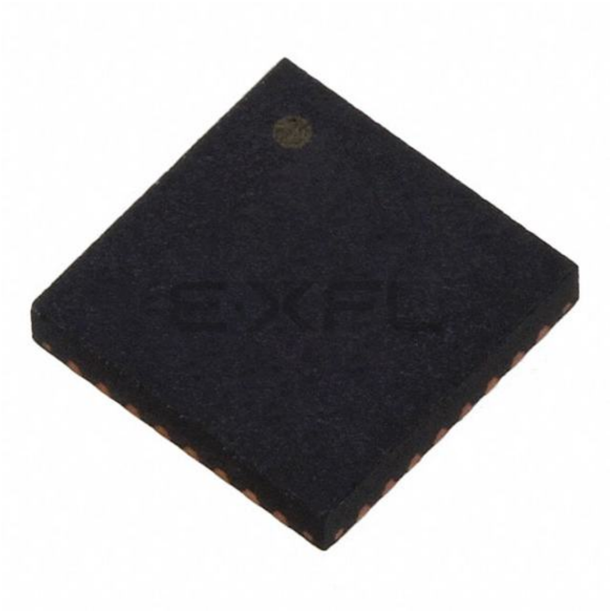
Silicon Labs - C8051F920-G-GM Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	8051
Core Size	8-Bit
Speed	25MHz
Connectivity	SMBus (2-Wire/I²C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	24
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4.25K x 8
Voltage - Supply (Vcc/Vdd)	0.9V ~ 3.6V
Data Converters	A/D 23x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f920-g-gm

1.2. Port Input/Output

Digital and analog resources are available through 24 I/O pins (C8051F930/20) or 16 I/O pins (C8051F931/21). Port pins are organized as three byte-wide ports. Port pins P0.0–P2.6 can be defined as digital or analog I/O. Digital I/O pins can be assigned to one of the internal digital resources or used as general purpose I/O (GPIO). Analog I/O pins are used by the internal analog resources. P2.7 can be used as GPIO and is shared with the C2 Interface Data signal (C2D). See Section “27. C2 Interface” on page 324 for more details.

The designer has complete control over which digital and analog functions are assigned to individual Port pins, limited only by the number of physical I/O pins. This resource assignment flexibility is achieved through the use of a Priority Crossbar Decoder. See Section “21.3. Priority Crossbar Decoder” on page 221 for more information on the Crossbar.

All Port I/Os are 5 V tolerant when used as digital inputs or open-drain outputs. For Port I/Os configured as push-pull outputs, current is sourced from the VDD/DC+ supply. Port I/Os used for analog functions can operate up to the VDD/DC+ supply voltage. See Section “21.1. Port I/O Modes of Operation” on page 217 for more information on Port I/O operating modes and the electrical specifications chapter for detailed electrical specifications.

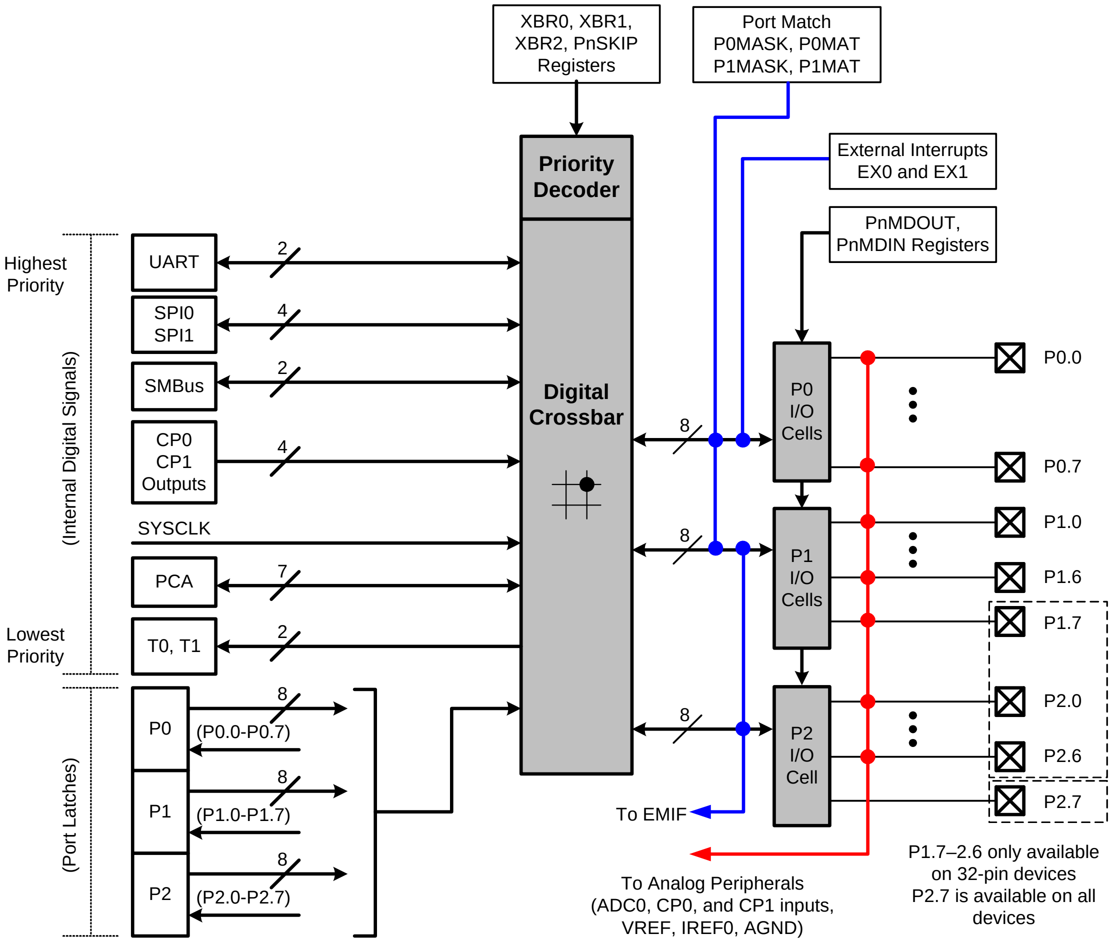


Figure 1.5. Port I/O Functional Block Diagram

Table 3.5. PCB Land Pattern

Dimension	MIN	MAX
C1	3.90	4.00
C2	3.90	4.00
E	0.50 BSC	
X1	0.20	0.30
X2	2.70	2.80
Y1	0.65	0.75
Y2	2.70	2.80

Notes:

General

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. This Land Pattern Design is based on the IPC-7351 guidelines.

Solder Mask Design

1. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 µm minimum, all the way around the pad.

Stencil Design

1. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
2. The stencil thickness should be 0.125 mm (5 mils).
3. The ratio of stencil aperture to land pad size should be 1:1 for all perimeter pads.
4. A 2 x 2 array of 1.0 x 1.0 mm square openings on 1.30 mm pitch should be used for the center ground pad.

Card Assembly

1. A No-Clean, Type-3 solder paste is recommended.
2. The recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

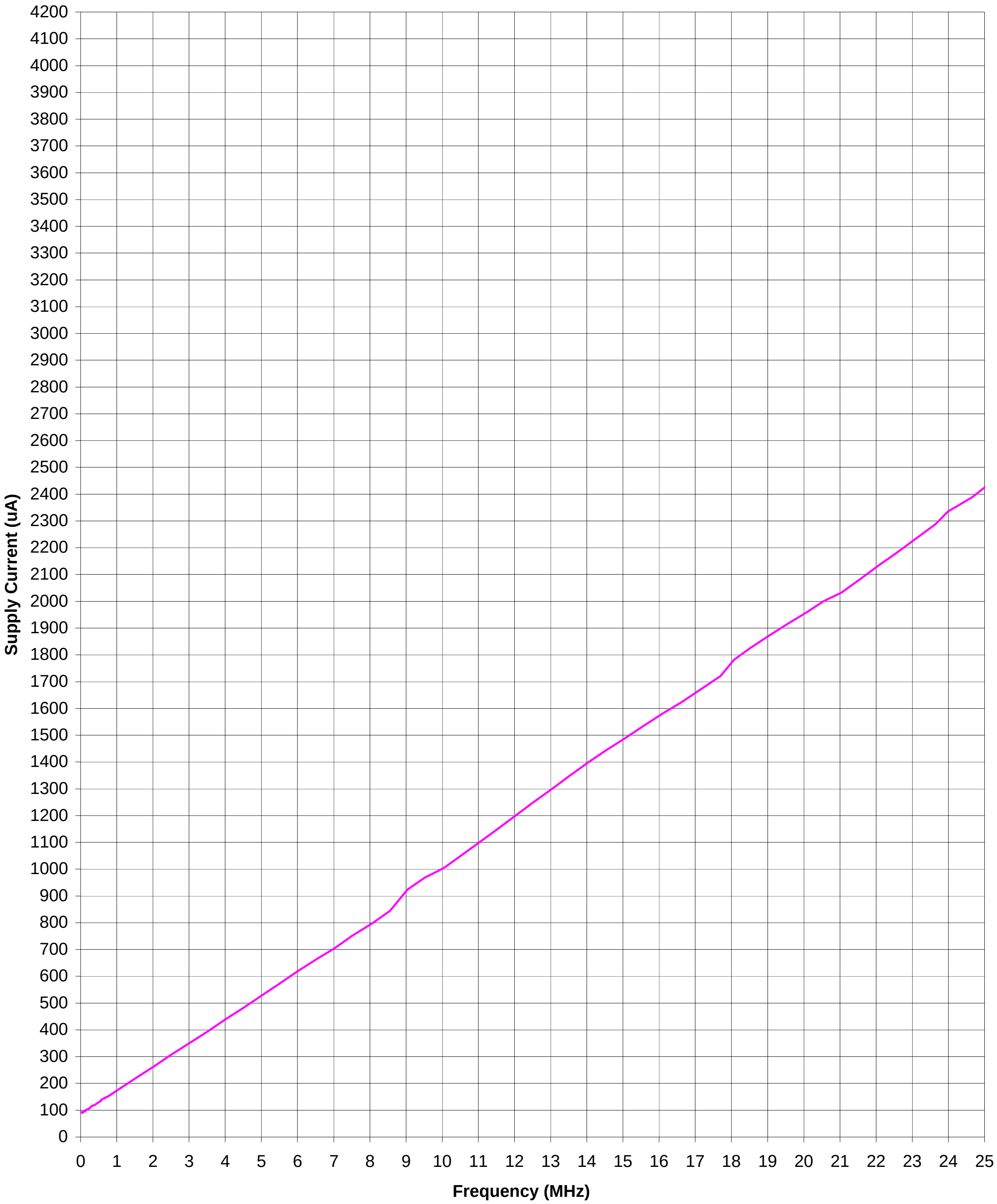


Figure 4.2. Idle Mode Current (External CMOS Clock)

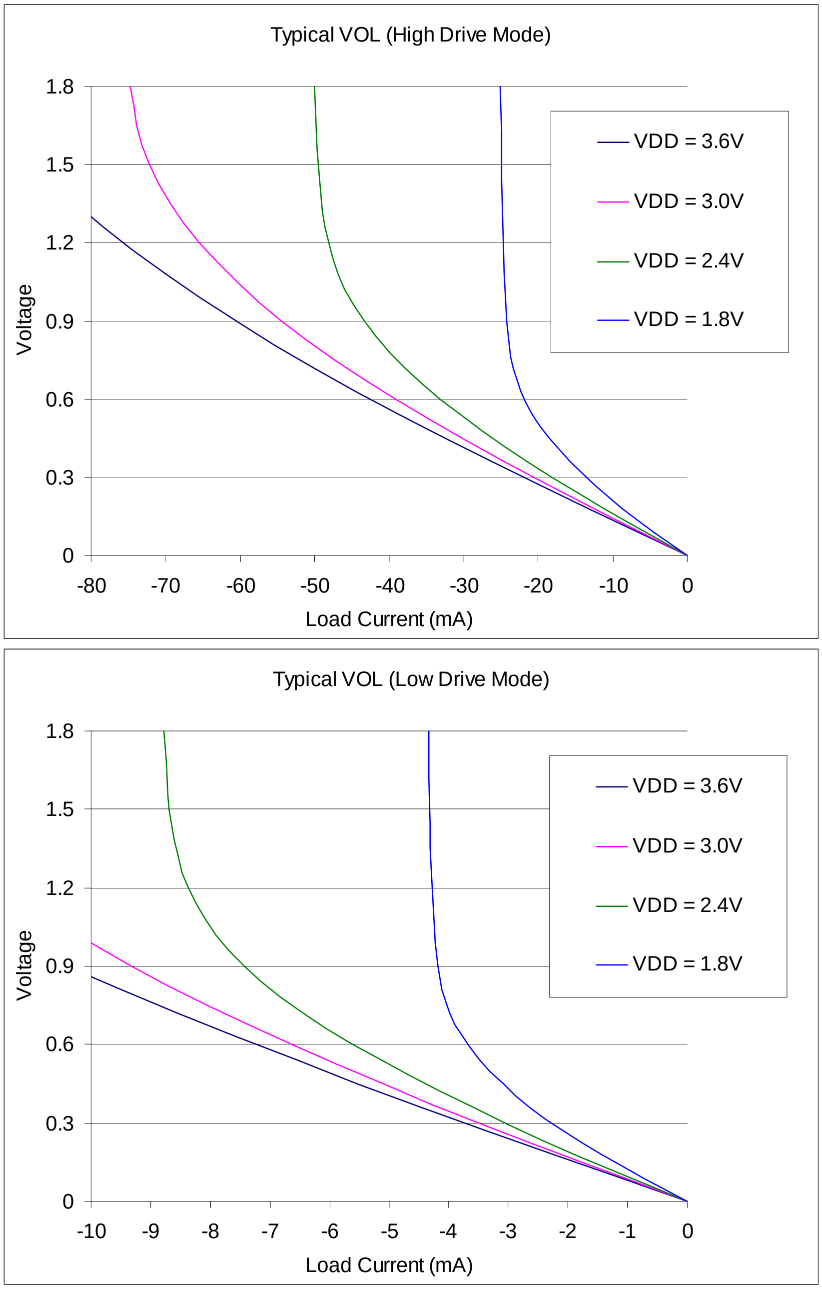


Figure 4.9. Typical VOL Curves, 1.8–3.6 V

Table 4.13. Comparator Electrical Characteristics

V_{DD} = 1.8 to 3.6 V, –40 to +85 °C unless otherwise noted.

Parameter	Conditions	Min	Typ	Max	Units
Response Time: Mode 0, V_{DD} = 2.4 V, V_{CM}^{*} = 1.2 V	CP0+ – CP0– = 100 mV	—	130	—	ns
	CP0+ – CP0– = –100 mV	—	200	—	ns
Response Time: Mode 1, V_{DD} = 2.4 V, V_{CM}^{*} = 1.2 V	CP0+ – CP0– = 100 mV	—	210	—	ns
	CP0+ – CP0– = –100 mV	—	410	—	ns
Response Time: Mode 2, V_{DD} = 2.4 V, V_{CM}^{*} = 1.2 V	CP0+ – CP0– = 100 mV	—	420	—	ns
	CP0+ – CP0– = –100 mV	—	1200	—	ns
Response Time: Mode 3, V_{DD} = 2.4 V, V_{CM}^{*} = 1.2 V	CP0+ – CP0– = 100 mV	—	1750	—	ns
	CP0+ – CP0– = –100 mV	—	6200	—	ns
Common-Mode Rejection Ratio		—	1.5	4	mV/V
Inverting or Non-Inverting Input Voltage Range		–0.25	—	V_{DD} + 0.25	V
Input Capacitance		—	12	—	pF
Input Bias Current		—	1	—	nA
Input Offset Voltage		–7	—	+7	mV
Power Supply					
Power Supply Rejection		—	0.1	—	mV/V
Power-up Time	VDD = 3.6 V	—	0.6	—	µs
	VDD = 3.0 V	—	1.0	—	µs
	VDD = 2.4 V	—	1.8	—	µs
	VDD = 1.8 V	—	10	—	µs
Supply Current at DC	Mode 0	—	23	—	µA
	Mode 1	—	8.8	—	µA
	Mode 2	—	2.6	—	µA
	Mode 3	—	0.4	—	µA
***Note:** Vcm is the common-mode voltage on CP0+ and CP0–.					

10.5.3. Split Mode with Bank Select

When EMI0CF.[3:2] are set to 10, the XRAM memory map is split into two areas, on-chip space and off-chip space.

- Effective addresses below the on-chip XRAM boundary will access on-chip XRAM space.
- Effective addresses above the on-chip XRAM boundary will access off-chip space.
- 8-bit MOVX operations use the contents of EMI0CN to determine whether the memory access is on-chip or off-chip. The upper 4-bits of the Address Bus A[11:8] are determined by EMI0CN, and the lower 8-bits of the Address Bus A[7:0] are determined by R0 or R1. **All 12-bits of the Address Bus A[11:0] are driven in “Bank Select” mode.**
- 16-bit MOVX operations use the contents of DPTR to determine whether the memory access is on-chip or off-chip, and the full 12-bits of the Address Bus A[11:0] are driven during the off-chip transaction.

10.5.4. External Only

When EMI0CF[3:2] are set to 11, all MOVX operations are directed to off-chip space. On-chip XRAM is not visible to the CPU. This mode is useful for accessing off-chip memory located between 0x0000 and the on-chip XRAM boundary.

- 8-bit MOVX operations ignore the contents of EMI0CN. The upper Address bits A[11:8] are not driven (identical behavior to an off-chip access in “Split Mode without Bank Select” described above). This allows the user to manipulate the upper address bits at will by setting the Port state directly. The lower 8-bits of the effective address A[7:0] are determined by the contents of R0 or R1.
- 16-bit MOVX operations use the contents of DPTR to determine the effective address A[11:0]. The full 12-bits of the Address Bus A[11:0] are driven during the off-chip transaction.

10.6. External Memory Interface Timing

The timing parameters of the External Memory Interface can be configured to enable connection to devices having different setup and hold time requirements. The Address Setup time, Address Hold time, $\overline{\text{RD}}$ and $\overline{\text{WR}}$ strobe widths, and in multiplexed mode, the width of the ALE pulse are all programmable in units of SYSCLK periods through EMI0TC, shown in SFR Definition 10.3, and EMI0CF[1:0].

The timing for an off-chip MOVX instruction can be calculated by adding 4 SYSCLK cycles to the timing parameters defined by the EMI0TC register. Assuming non-multiplexed operation, the minimum execution time for an off-chip XRAM operation is 5 SYSCLK cycles (1 SYSCLK for $\overline{\text{RD}}$ or $\overline{\text{WR}}$ pulse + 4 SYSCLKs). For multiplexed operations, the Address Latch Enable signal will require a minimum of 2 additional SYSCLK cycles. Therefore, the minimum execution time of an off-chip XRAM operation in multiplexed mode is 7 SYSCLK cycles (2 SYSCLKs for ALE, 1 for $\overline{\text{RD}}$ or $\overline{\text{WR}}$ + 4 SYSCLKs). The programmable setup and hold times default to the maximum delay settings after a reset.

Table 10.1 lists the ac parameters for the External Memory Interface, and Figure 10.1 through Figure 10.6 show the timing diagrams for the different External Memory Interface modes and MOVX operations. See Section “21. Port Input/Output” on page 216 to determine which port pins are mapped to the ADDR[11:8], AD[7:0], ALE, $\overline{\text{RD}}$, and $\overline{\text{WR}}$ signals.

13.1.2. Flash Erase Procedure

The Flash memory is organized in 1024-byte pages. The erase operation applies to an entire page (setting all bytes in the page to 0xFF). To erase an entire 1024-byte page, perform the following steps:

1. Save current interrupt state and disable interrupts.
2. Set the PSEE bit (register PSCTL).
3. Set the PSWE bit (register PSCTL).
4. Write the first key code to FLKEY: 0xA5.
5. Write the second key code to FLKEY: 0xF1.
6. Using the MOVX instruction, write a data byte to any location within the 1024-byte page to be erased.
7. Clear the PSWE and PSEE bits.
8. Restore previous interrupt state.

Steps 4–6 must be repeated for each 1024-byte page to be erased.

Notes:

1. Future 16 and 8 kB derivatives in this product family will use a 512-byte page size. To maintain code compatibility across the entire family, the erase procedure should be performed on each 512-byte section of memory.
2. Flash security settings may prevent erasure of some Flash pages, such as the reserved area and the page containing the lock bytes. For a summary of Flash security settings and restrictions affecting Flash erase operations, please see Section “13.3. Security Options” on page 150.
3. 8-bit MOVX instructions cannot be used to erase or write to Flash memory at addresses higher than 0x00FF.

13.1.3. Flash Write Procedure

A write to Flash memory can clear bits to logic 0 but cannot set them; only an erase operation can set bits to logic 1 in Flash. **A byte location to be programmed should be erased before a new value is written.**

The recommended procedure for writing a single byte in Flash is as follows:

1. Save current interrupt state and disable interrupts.
2. Ensure that the Flash byte has been erased (has a value of 0xFF).
3. Set the PSWE bit (register PSCTL).
4. Clear the PSEE bit (register PSCTL).
5. Write the first key code to FLKEY: 0xA5.
6. Write the second key code to FLKEY: 0xF1.
7. Using the MOVX instruction, write a single data byte to the desired location within the 1024-byte sector.
8. Clear the PSWE bit.
9. Restore previous interrupt state.

Steps 5–7 must be repeated for each byte to be written.

Notes:

1. Future 16 and 8 kB derivatives in this product family will use a 512-byte page size. To maintain code compatibility across the entire family, the erase procedure should be performed on each 512-byte section of memory.
2. Flash security settings may prevent writes to some areas of Flash, such as the reserved area. For a summary of Flash security settings and restrictions affecting Flash write operations, please see Section “13.3. Security Options” on page 150.

14.7. Determining the Event that Caused the Last Wakeup

When waking from idle mode, the CPU will vector to the interrupt which caused it to wake up. When waking from stop mode, the RSTSRC register may be read to determine the cause of the last reset.

Upon exit from suspend or sleep mode, the wake-up flags in the PMU0CF register can be read to determine the event which caused the device to wake up. After waking up, the wake-up flags will continue to be updated if any of the wake-up events occur. Wake-up flags are always updated, even if they are not enabled as wake-up sources.

All wake-up flags enabled as wake-up sources in PMU0CF must be cleared before the device can enter suspend or sleep mode. After clearing the wake-up flags, each of the enabled wake-up events should be checked in the individual peripherals to ensure that a wake-up event did not occur while the wake-up flags were being cleared.

18.7. Flash Error Reset

If a Flash read/write/erase or program read targets an illegal address, a system reset is generated. This may occur due to any of the following:

- A Flash write or erase is attempted above user code space. This occurs when PSWE is set to 1 and a MOVX write operation targets an address above the Lock Byte address.
- A Flash read is attempted above user code space. This occurs when a MOVC operation targets an address above the Lock Byte address.
- A Program read is attempted above user code space. This occurs when user code attempts to branch to an address above the Lock Byte address.
- A Flash read, write or erase attempt is restricted due to a Flash security setting (see Section "13.3. Security Options" on page 150).
- A Flash write or erase is attempted while the V_{DD} Monitor is disabled.

The FERROR bit (RSTSRC.6) is set following a Flash error reset. The state of the $\overline{\text{RST}}$ pin is unaffected by this reset.

18.8. SmaRTClock (Real Time Clock) Reset

The SmaRTClock can generate a system reset on two events: SmaRTClock Oscillator Fail or SmaRTClock Alarm. The SmaRTClock Oscillator Fail event occurs when the SmaRTClock Missing Clock Detector is enabled and the SmaRTClock clock is below approximately 20 kHz. A SmaRTClock alarm event occurs when the SmaRTClock Alarm is enabled and the SmaRTClock timer value matches the ALARMn registers. The SmaRTClock can be configured as a reset source by writing a 1 to the RTC0RE flag (RSTSRC.7). The SmaRTClock reset remains functional even when the device is in the low power Suspend or Sleep mode. The state of the $\overline{\text{RST}}$ pin is unaffected by this reset.

18.9. Software Reset

Software may force a reset by writing a 1 to the SWRSF bit (RSTSRC.4). The SWRSF bit will read 1 following a software forced reset. The state of the $\overline{\text{RST}}$ pin is unaffected by this reset.

20.3.2. Setting a SmaRTClock Alarm

The SmaRTClock alarm function compares the 32-bit value of SmaRTClock Timer to the value of the ALARMn registers. An alarm event is triggered if the SmaRTClock timer is **equal to** the ALARMn registers. If Auto Reset is enabled, the 32-bit timer will be cleared to zero one SmaRTClock cycle after the alarm event.

The SmaRTClock alarm event can be configured to reset the MCU, wake it up from a low power mode, or generate an interrupt. See Section “12. Interrupt Handler” on page 136, Section “14. Power Management” on page 159, and Section “18. Reset Sources” on page 184 for more information.

The following steps can be used to set up a SmaRTClock Alarm:

1. Disable SmaRTClock Alarm Events (RTC0AEN = 0).
2. Set the ALARMn registers to the desired value.
3. Enable SmaRTClock Alarm Events (RTC0AEN = 1).

Notes:

- The ALRM bit, which is used as the SmaRTClock Alarm Event flag, is cleared by disabling SmaRTClock Alarm Events (RTC0AEN = 0).
- If AutoReset is disabled, disabling (RTC0AEN = 0) then Re-enabling Alarm Events (RTC0AEN = 1) after a SmaRTClock Alarm without modifying ALARMn registers will automatically schedule the next alarm after 2^32 SmaRTClock cycles (approximately 36 hours using a 32.768 kHz crystal).
- The SmaRTClock Alarm Event flag will remain asserted for a maximum of one SmaRTClock cycle. See Section “14. Power Management” on page 159 for information on how to capture a SmaRTClock Alarm event using a flag which is not automatically cleared by hardware.

20.3.3. Software Considerations for using the SmaRTClock Timer and Alarm

The SmaRTClock timer and alarm have two operating modes to suit varying applications. The two modes are described below:

Mode 1:
The first mode uses the SmaRTClock timer as a perpetual timebase which is never reset to zero. Every 36 hours, the timer is allowed to overflow without being stopped or disrupted. The alarm interval is software managed and is added to the ALRMn registers by software after each alarm. This allows the alarm match value to always stay ahead of the timer by one software managed interval. If software uses 32-bit unsigned addition to increment the alarm match value, then it does not need to handle overflows since both the timer and the alarm match value will overflow in the same manner.

This mode is ideal for applications which have a long alarm interval (e.g. 24 or 36 hours) and/or have a need for a perpetual timebase. An example of an application that needs a perpetual timebase is one whose wake-up interval is constantly changing. For these applications, software can keep track of the number of timer overflows in a 16-bit variable, extending the 32-bit (36 hour) timer to a 48-bit (272 year) perpetual timebase.

Mode 2:
The second mode uses the SmaRTClock timer as a general purpose up counter which is auto reset to zero by hardware after each alarm. The alarm interval is managed by hardware and stored in the ALRMn registers. Software only needs to set the alarm interval once during device initialization. After each alarm, software should keep a count of the number of alarms that have occurred in order to keep track of time.

This mode is ideal for applications that require minimal software intervention and/or have a fixed alarm interval. This mode is the most power efficient since it requires less CPU time per alarm.

Internal Register Definition 20.6. RTC0XCF: SmaRTClock Oscillator Configuration

Bit	7	6	5	4	3	2	1	0
Name	AUTOSTP	LOADRDY			LOADCAP			
Type	R/W	R	R	R	R/W			
Reset	0	0	0	0	Varies	Varies	Varies	Varies

SmaRTClock Address = 0x06

Bit	Name	Function
7	AUTOSTP	**Automatic Load Capacitance Stepping Enable.** Enables/disables automatic load capacitance stepping. 0: Load capacitance stepping disabled. 1: Load capacitance stepping enabled.
6	LOADRDY	**Load Capacitance Ready Indicator.** Set by hardware when the load capacitance matches the programmed value. 0: Load capacitance is currently stepping. 1: Load capacitance has reached it programmed value.
5:4	Unused	**Unused.** Read = 00b; Write = Don't Care.
3:0	LOADCAP	**Load Capacitance Programmed Value.** Holds the user's desired value of the load capacitance. See Table 20.2 on page 207.

Internal Register Definition 20.7. RTC0PIN: SmaRTClock Pin Configuration

Bit	7	6	5	4	3	2	1	0
Name	RTC0PIN							
Type	W							
Reset	0	1	1	0	0	1	1	1

SmaRTClock Address = 0x07

Bit	Name	Function
7:0	RTC0PIN	**SmaRTClock Pin Configuration.** Writing 0xE7 to this register forces XTAL3 and XTAL4 to be internally shorted for use with Self Oscillate Mode. Writing 0x67 returns XTAL3 and XTAL4 to their normal configuration.

24.5. Serial Clock Phase and Polarity

Four combinations of serial clock phase and polarity can be selected using the clock control bits in the SPI Configuration Register (SPInCFG). The CKPHA bit (SPInCFG.5) selects one of two clock phases (edge used to latch the data). The CKPOL bit (SPInCFG.4) selects between an active-high or active-low clock. Both master and slave devices must be configured to use the same clock phase and polarity. SPI0 should be disabled (by clearing the SPIENn bit, SPInCN.0) when changing the clock phase or polarity. The clock and data line relationships for master mode are shown in Figure 24.5. For slave mode, the clock and data relationships are shown in Figure 24.6 and Figure 24.7. Note that CKPHA must be set to 0 on both the master and slave SPI when communicating between two of the following devices: C8051F04x, C8051F06x, C8051F12x, C8051F31x, C8051F32x, and C8051F33x.

The SPIn Clock Rate Register (SPInCKR) as shown in SFR Definition 24.3 controls the master mode serial clock frequency. This register is ignored when operating in slave mode. When the SPI is configured as a master, the maximum data transfer rate (bits/sec) is one-half the system clock frequency or 12.5 MHz, whichever is slower. When the SPI is configured as a slave, the maximum data transfer rate (bits/sec) for full-duplex operation is 1/10 the system clock frequency, provided that the master issues SCK, NSS (in 4-wire slave mode), and the serial input data synchronously with the slave's system clock. If the master issues SCK, NSS, and the serial input data asynchronously, the maximum data transfer rate (bits/sec) must be less than 1/10 the system clock frequency. In the special case where the master only wants to transmit data to the slave and does not need to receive data from the slave (i.e. half-duplex operation), the SPI slave can receive data at a maximum data transfer rate (bits/sec) of 1/4 the system clock frequency. This is provided that the master issues SCK, NSS, and the serial input data synchronously with the slave's system clock.

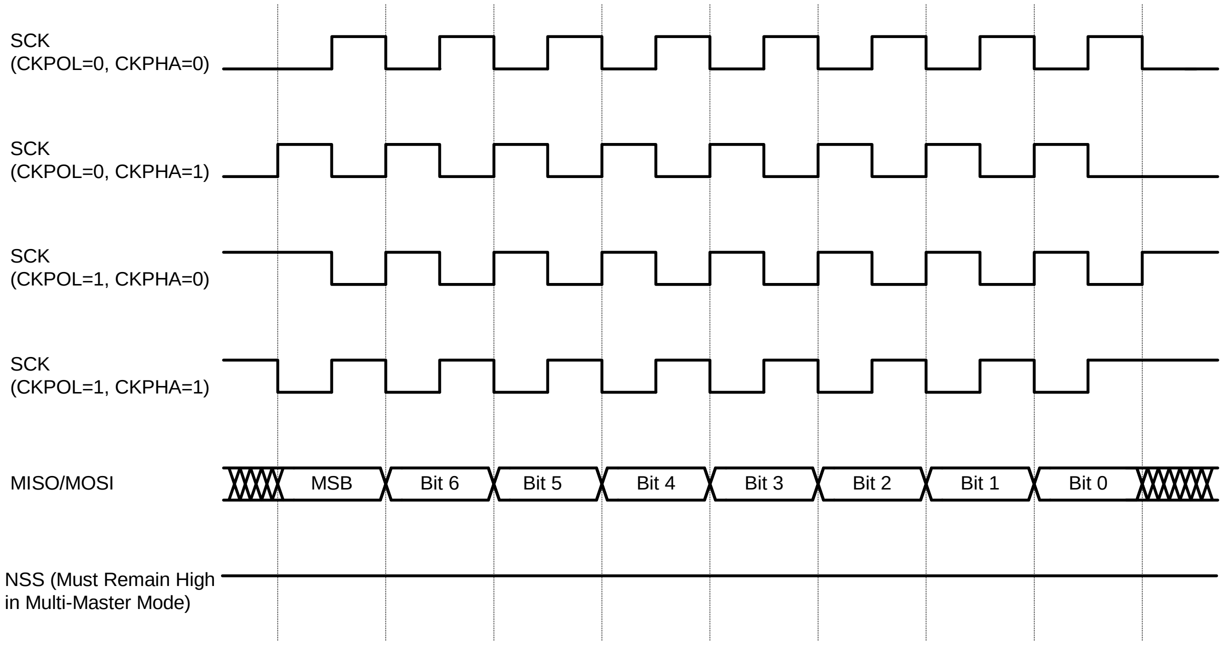


Figure 24.5. Master Mode Data/Clock Timing

25.1. Timer 0 and Timer 1

Each timer is implemented as a 16-bit register accessed as two separate bytes: a low byte (TL0 or TL1) and a high byte (TH0 or TH1). The Counter/Timer Control register (TCON) is used to enable Timer 0 and Timer 1 as well as indicate status. Timer 0 interrupts can be enabled by setting the ET0 bit in the IE register (Section “12.5. Interrupt Register Descriptions” on page 139); Timer 1 interrupts can be enabled by setting the ET1 bit in the IE register (Section “12.5. Interrupt Register Descriptions” on page 139). Both counter/timers operate in one of four primary modes selected by setting the Mode Select bits T1M1–T0M0 in the Counter/Timer Mode register (TMOD). Each timer can be configured independently. Each operating mode is described below.

25.1.1. Mode 0: 13-bit Counter/Timer

Timer 0 and Timer 1 operate as 13-bit counter/timers in Mode 0. The following describes the configuration and operation of Timer 0. However, both timers operate identically, and Timer 1 is configured in the same manner as described for Timer 0.

The TH0 register holds the eight MSBs of the 13-bit counter/timer. TL0 holds the five LSBs in bit positions TL0.4–TL0.0. The three upper bits of TL0 (TL0.7–TL0.5) are indeterminate and should be masked out or ignored when reading. As the 13-bit timer register increments and overflows from 0x1FFF (all ones) to 0x0000, the timer overflow flag TF0 (TCON.5) is set and an interrupt will occur if Timer 0 interrupts are enabled.

The C/T0 bit (TMOD.2) selects the counter/timer's clock source. When C/T0 is set to logic 1, high-to-low transitions at the selected Timer 0 input pin (T0) increment the timer register (Refer to Section “21.3. Priority Crossbar Decoder” on page 221 for information on selecting and configuring external I/O pins). Clearing C/T selects the clock defined by the T0M bit (CKCON.3). When T0M is set, Timer 0 is clocked by the system clock. When T0M is cleared, Timer 0 is clocked by the source selected by the Clock Scale bits in CKCON (see SFR Definition 25.1).

Setting the TR0 bit (TCON.4) enables the timer when either GATE0 (TMOD.3) is logic 0 or the input signal $\overline{\text{INT0}}$ is active as defined by bit IN0PL in register IT01CF (see SFR Definition 12.7). Setting GATE0 to 1 allows the timer to be controlled by the external input signal $\overline{\text{INT0}}$ (see Section “12.5. Interrupt Register Descriptions” on page 139), facilitating pulse width measurements

Table 25.1. Timer 0 Running Modes

TR0	GATE0	$\overline{\text{INT0}}$	Counter/Timer
0	X	X	Disabled
1	0	X	Enabled
1	1	0	Disabled
1	1	1	Enabled
Note: X = Don't Care			

Setting TR0 does not force the timer to reset. The timer registers should be loaded with the desired initial value before the timer is enabled.

TL1 and TH1 form the 13-bit register for Timer 1 in the same manner as described above for TL0 and TH0. Timer 1 is configured and controlled using the relevant TCON and TMOD bits just as with Timer 0. The input signal $\overline{\text{INT1}}$ is used with Timer 1; the $\overline{\text{INT1}}$ polarity is defined by bit IN1PL in register IT01CF (see SFR Definition 12.7).

SFR Definition 25.2. TCON: Timer Control

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Name	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Page = 0x0; SFR Address = 0x88; Bit-Addressable

Bit	Name	Function
7	TF1	**Timer 1 Overflow Flag.** Set to 1 by hardware when Timer 1 overflows. This flag can be cleared by software but is automatically cleared when the CPU vectors to the Timer 1 interrupt service routine.
6	TR1	**Timer 1 Run Control.** Timer 1 is enabled by setting this bit to 1.
5	TF0	**Timer 0 Overflow Flag.** Set to 1 by hardware when Timer 0 overflows. This flag can be cleared by software but is automatically cleared when the CPU vectors to the Timer 0 interrupt service routine.
4	TR0	**Timer 0 Run Control.** Timer 0 is enabled by setting this bit to 1.
3	IE1	**External Interrupt 1.** This flag is set by hardware when an edge/level of type defined by IT1 is detected. It can be cleared by software but is automatically cleared when the CPU vectors to the External Interrupt 1 service routine in edge-triggered mode.
2	IT1	**Interrupt 1 Type Select.** This bit selects whether the configured $\overline{\text{INT1}}$ interrupt will be edge or level sensitive. $\overline{\text{INT1}}$ is configured active low or high by the IN1PL bit in the IT01CF register (see SFR Definition 12.7). 0: $\overline{\text{INT1}}$ is level triggered. 1: $\overline{\text{INT1}}$ is edge triggered.
1	IE0	**External Interrupt 0.** This flag is set by hardware when an edge/level of type defined by IT1 is detected. It can be cleared by software but is automatically cleared when the CPU vectors to the External Interrupt 0 service routine in edge-triggered mode.
0	IT0	**Interrupt 0 Type Select.** This bit selects whether the configured $\overline{\text{INT0}}$ interrupt will be edge or level sensitive. $\overline{\text{INT0}}$ is configured active low or high by the IN0PL bit in register IT01CF (see SFR Definition 12.7). 0: $\overline{\text{INT0}}$ is level triggered. 1: $\overline{\text{INT0}}$ is edge triggered.

26.3.2. Software Timer (Compare) Mode

In Software Timer mode, the PCA counter/timer value is compared to the module's 16-bit capture/compare register (PCA0CPHn and PCA0CPLn). When a match occurs, the Capture/Compare Flag (CCFn) in PCA0CN is set to logic 1. An interrupt request is generated if the CCFn interrupt for that module is enabled. The CCFn bit is not automatically cleared by hardware when the CPU vectors to the interrupt service routine, and must be cleared by software. Setting the ECOMn and MATn bits in the PCA0CPMn register enables Software Timer mode.

Important Note About Capture/Compare Registers: When writing a 16-bit value to the PCA0 Capture/Compare registers, the low byte should always be written first. Writing to PCA0CPLn clears the ECOMn bit to 0; writing to PCA0CPHn sets ECOMn to 1.

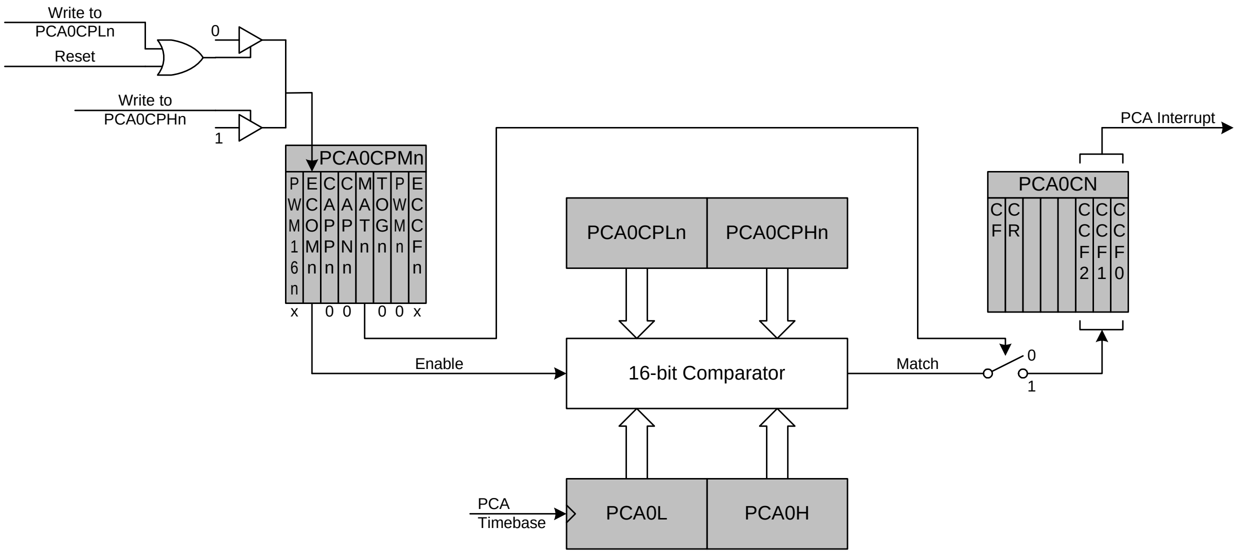


Figure 26.5. PCA Software Timer Mode Diagram

SFR Definition 26.7. PCA0CPLn: PCA Capture Module Low Byte

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Name	PCA0CPn[7:0]							
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Addresses: PCA0CPL0 = 0xFB, PCA0CPL1 = 0xE9, PCA0CPL2 = 0xEB,
PCA0CPL3 = 0xED, PCA0CPL4 = 0xFD, PCA0CPL5 = 0xD2

SFR Pages: PCA0CPL0 = 0x0, PCA0CPL1 = 0x0, PCA0CPL2 = 0x0,
PCA0CPL3 = 0x0, PCA0CPL4 = 0x0, PCA0CPL5 = 0x0

Bit	Name	Function
7:0	PCA0CPn[7:0]	**PCA Capture Module Low Byte.** The PCA0CPLn register holds the low byte (LSB) of the 16-bit capture module n. This register address also allows access to the low byte of the corresponding PCA channel's auto-reload value for 9, 10, or 11-bit PWM mode. The ARSEL bit in register PCA0PWM controls which register is accessed.
Note: A write to this register will clear the module's ECOMn bit to a 0.		

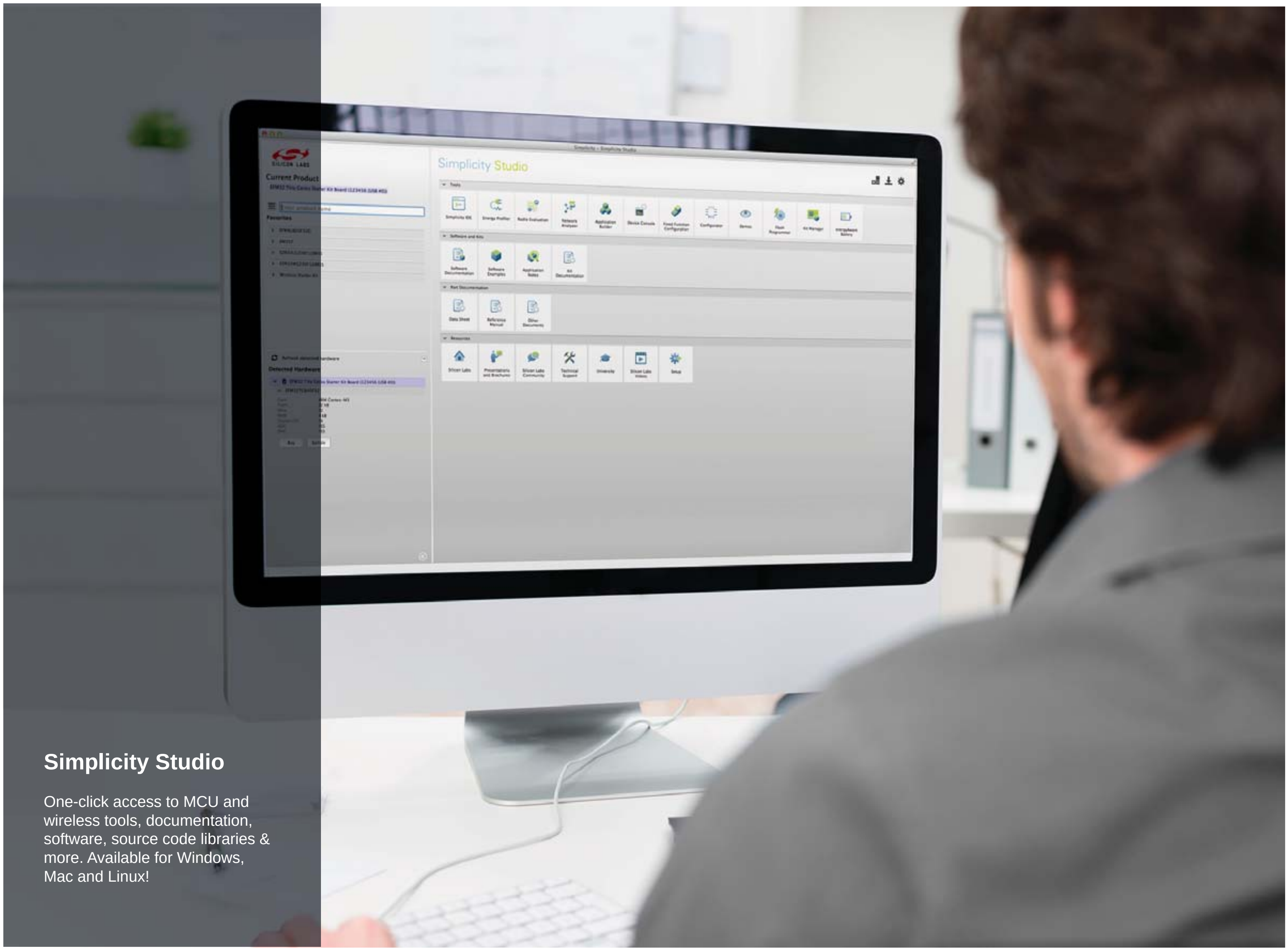
SFR Definition 26.8. PCA0CPHn: PCA Capture Module High Byte

Bit	**7**	**6**	**5**	**4**	**3**	**2**	**1**	**0**
Name	PCA0CPn[15:8]							
Type	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Addresses: PCA0CPH0 = 0xFC, PCA0CPH1 = 0xEA, PCA0CPH2 = 0xEC,
PCA0CPH3 = 0xEE, PCA0CPH4 = 0xFE, PCA0CPH5 = 0xD3

SFR Pages: PCA0CPH0 = 0x0, PCA0CPH1 = 0x0, PCA0CPH2 = 0x0,
PCA0CPH3 = 0x0, PCA0CPH4 = 0x0, PCA0CPH5 = 0x0

Bit	Name	Function
7:0	PCA0CPn[15:8]	**PCA Capture Module High Byte.** The PCA0CPHn register holds the high byte (MSB) of the 16-bit capture module n. This register address also allows access to the high byte of the corresponding PCA channel's auto-reload value for 9, 10, or 11-bit PWM mode. The ARSEL bit in register PCA0PWM controls which register is accessed.
Note: A write to this register will set the module's ECOMn bit to a 1.		



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